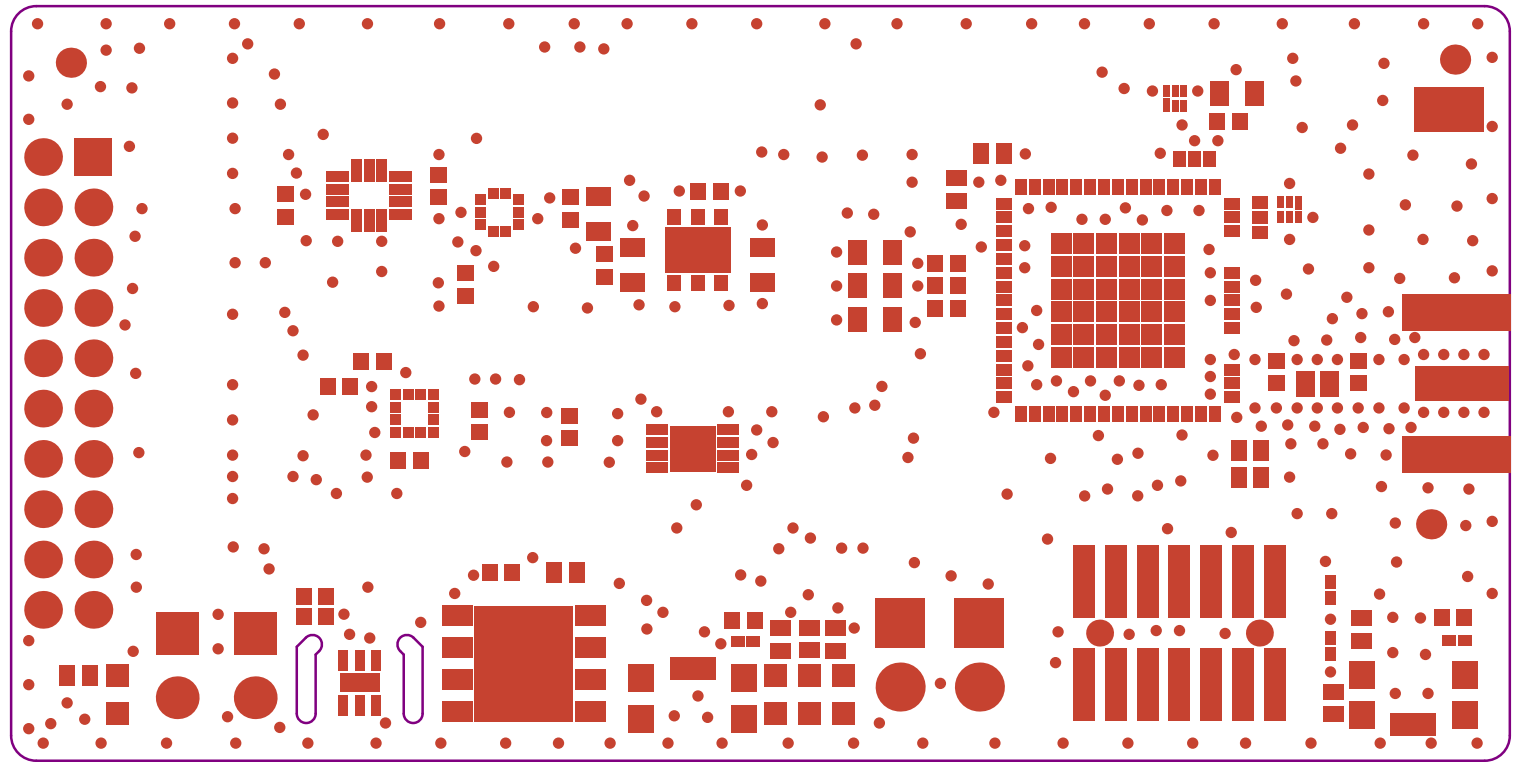


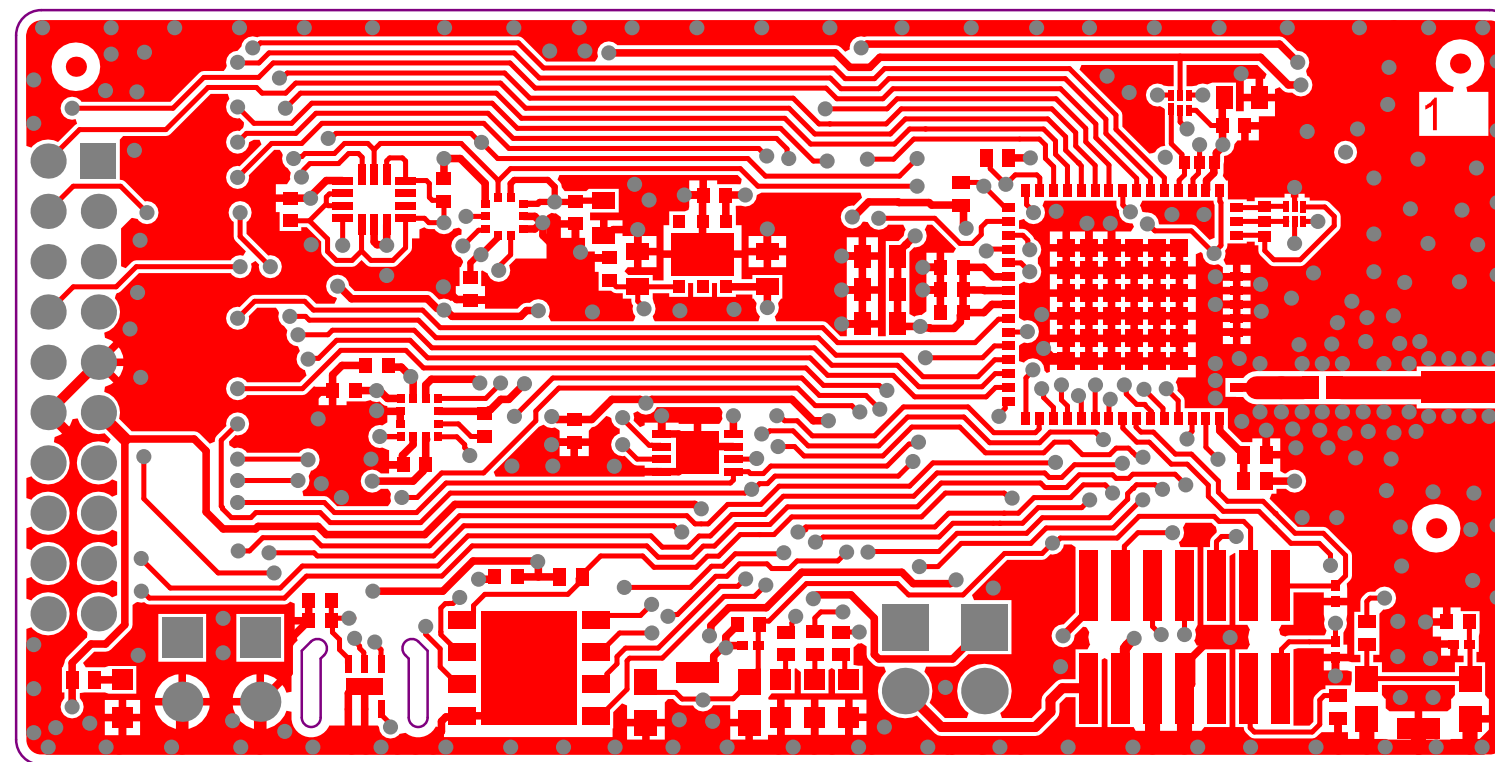
Top Overlay

.GTO



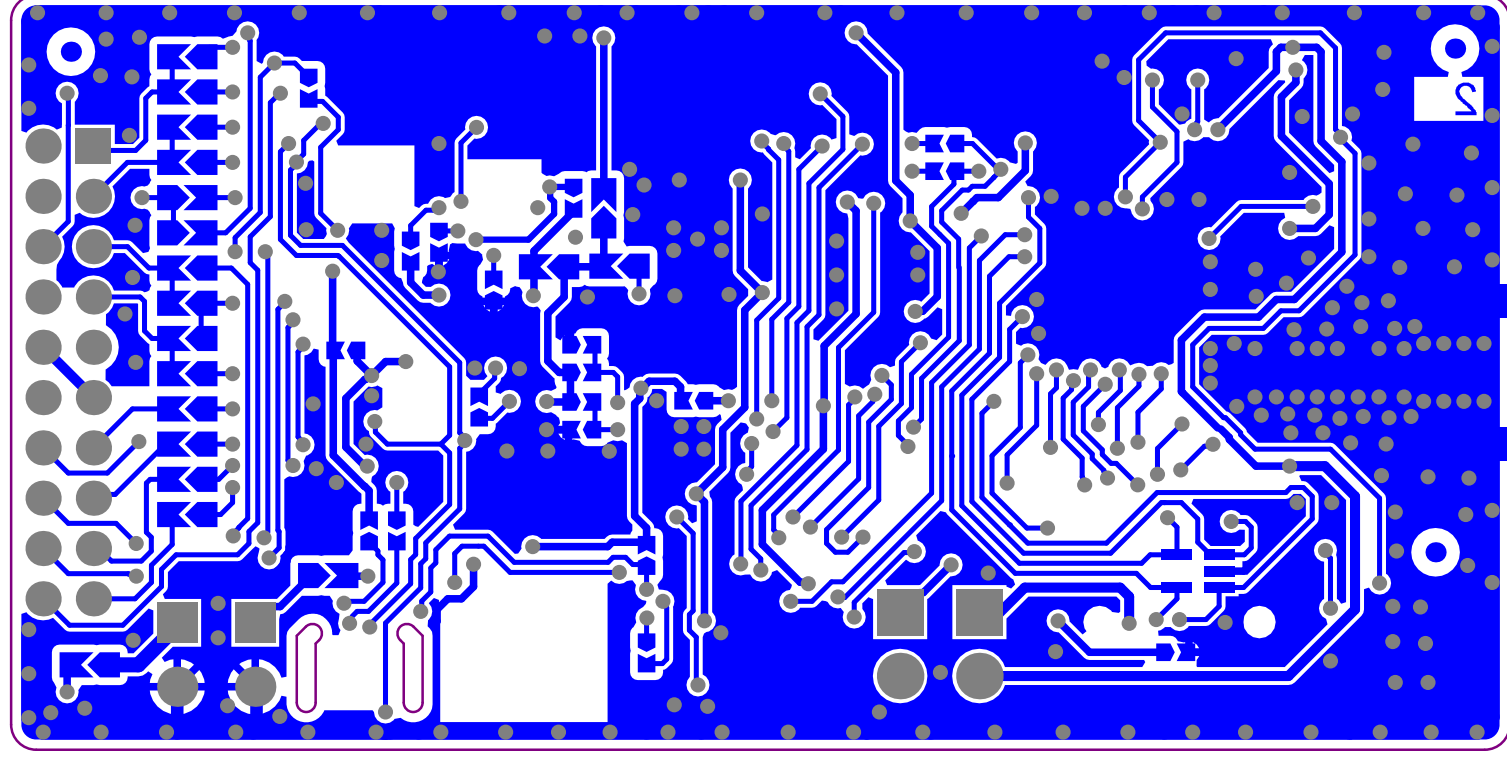
Top Solder

.GTS



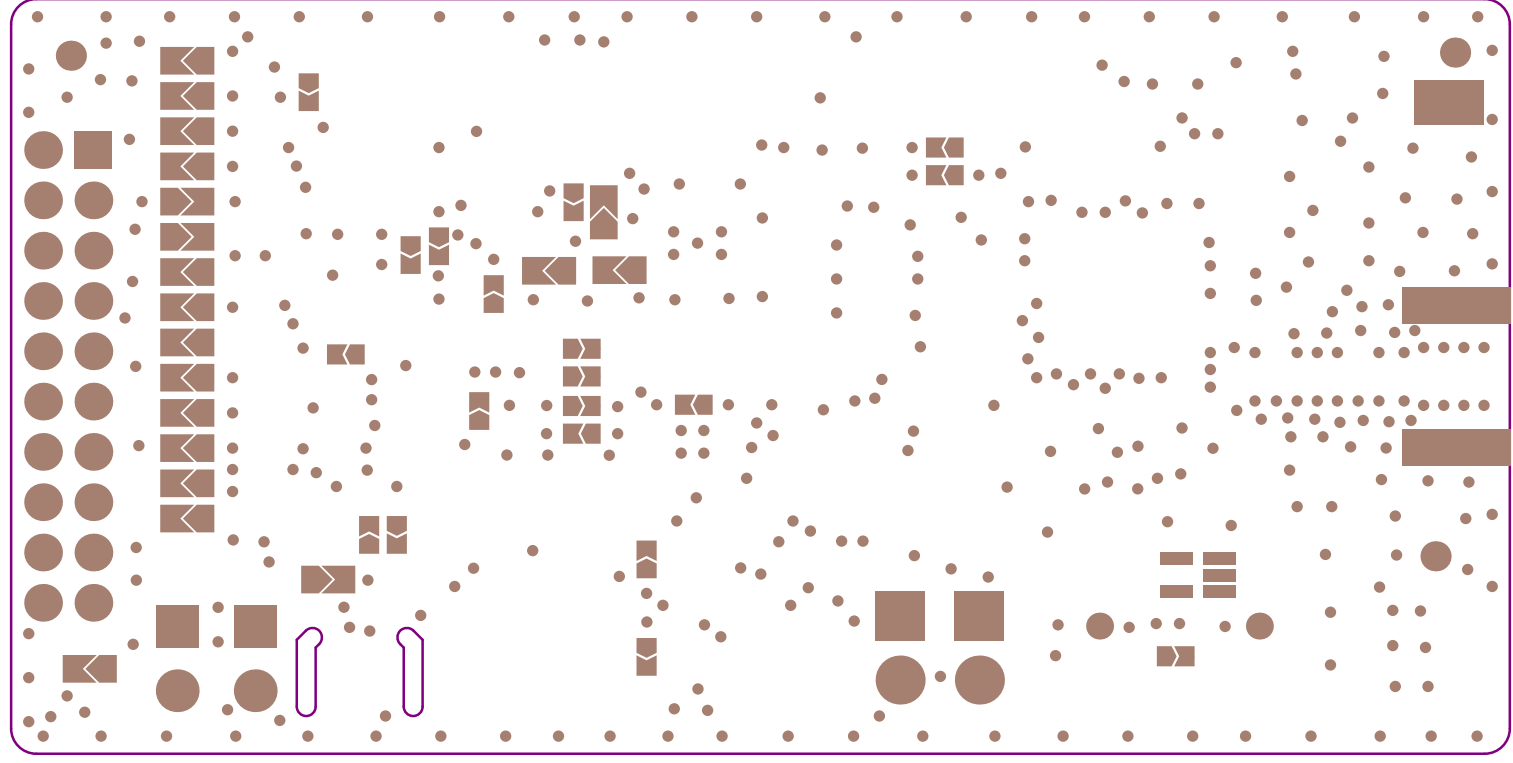
Top Layer

.GTL



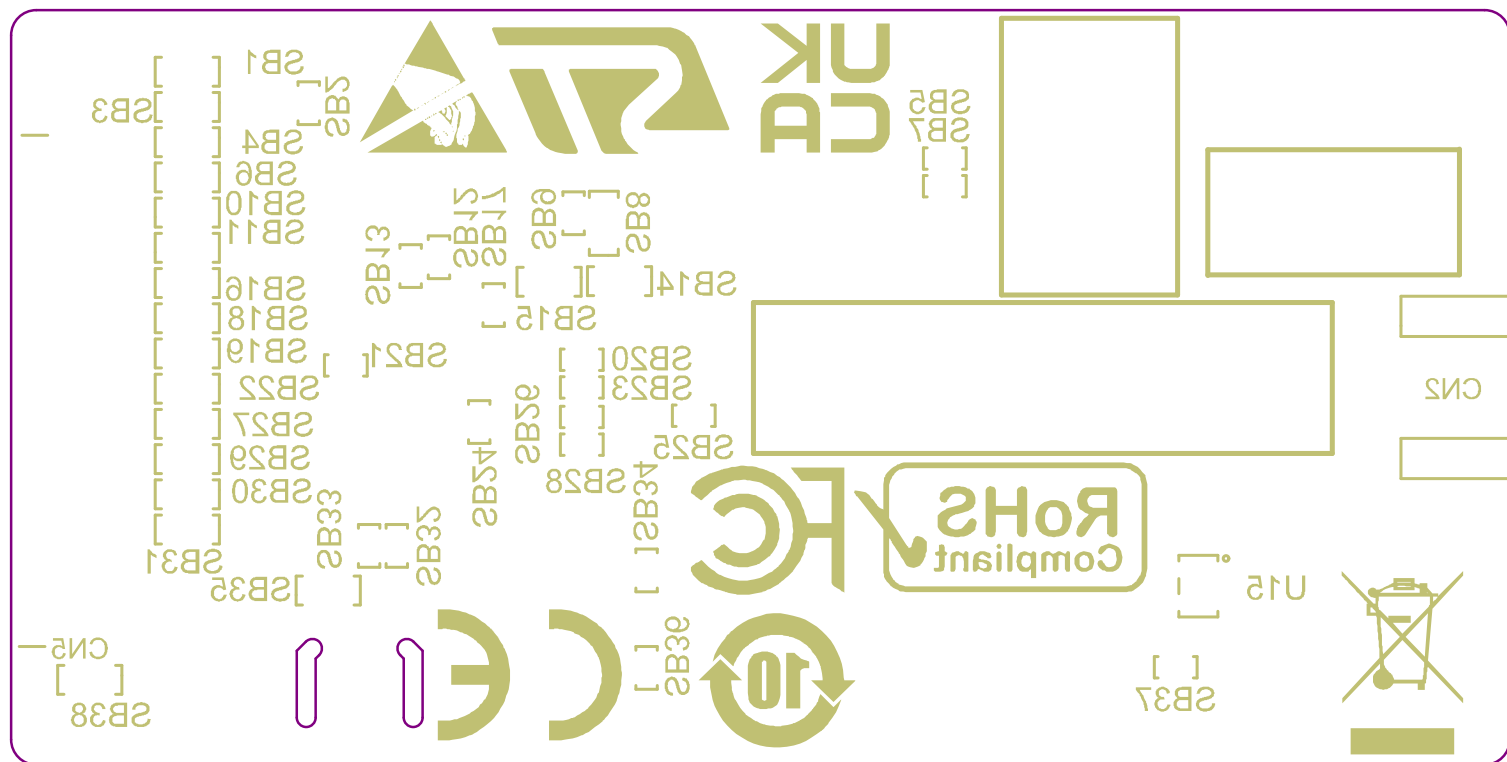
Bottom Layer

.GBL



.GBS

Bottom Solder



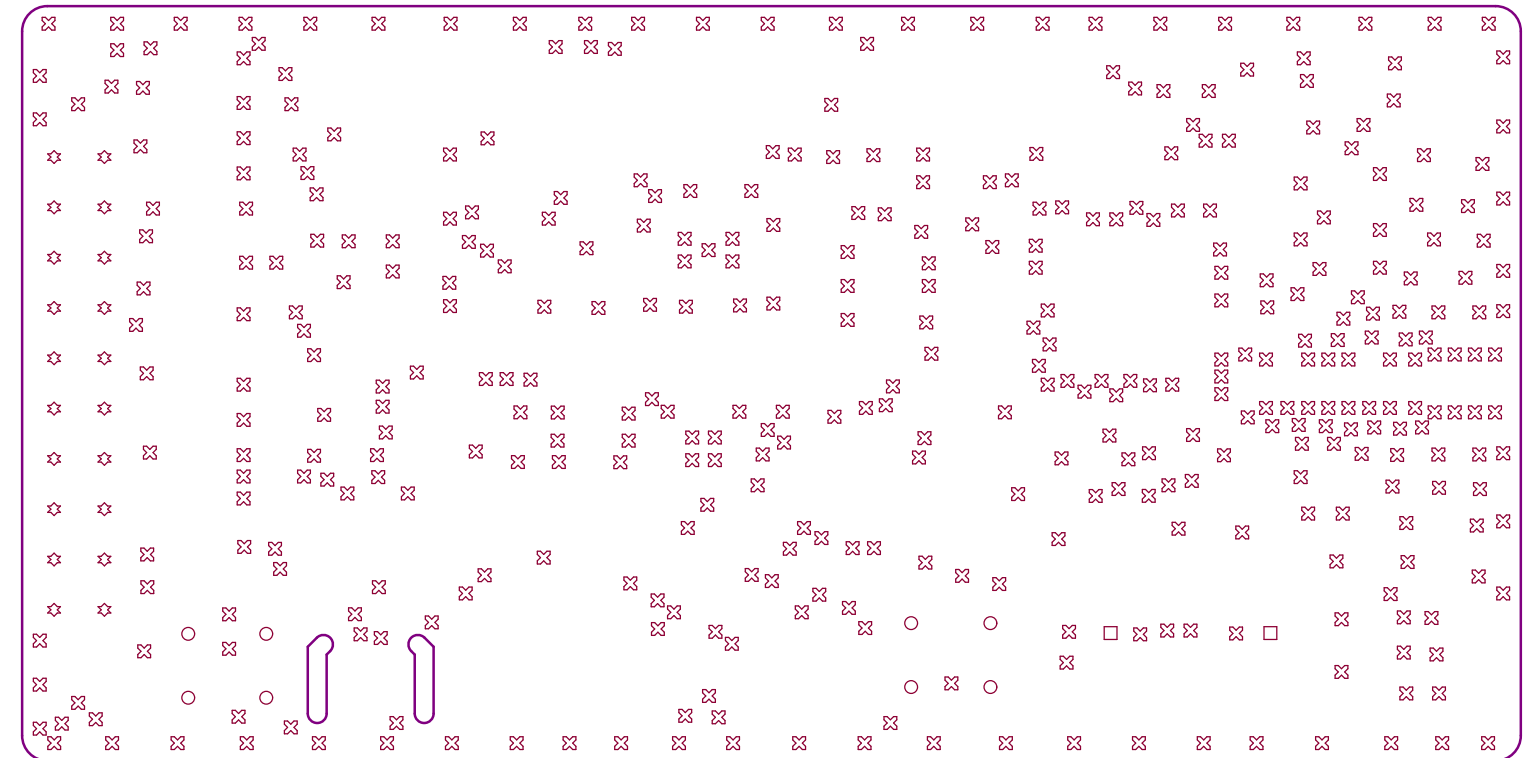
BOG

THE COMPONENTS WITH PLATED THROUGH HOLE (PTH) MAY BE WELDED (CABLED) IN "PIN-IN-PASTE" MODE (IF NECESSARY)
""TOP PASTE""

MINIMUM PARAMETERS	PCB : TYPE 2
DEFAULT TRACKS : 0.20mm GAPS : 0.20mm	ASPECT-RATIO, AXE Z : < 6:1 LEVEL "A"

PCB SPECIFICATIONS :

- A. MATERIAL : FR-4 ☐ TG-170 ☐ TG-150 ☒ TG-140
B. MATERIAL FAMILY : N/A
C. SOLDERMASK COLOR : ☐ GREEN ☐ WHITE ☐ RED ☒ Blue ink PANTONE 2955
D. SILKSCREEN COLOR : ☒ WHITE ☐ YELLOW ☐ BLACK ☐ Blue ink PANTONE 2955
E. SURFACE FINISH : ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN
☐ HASL ☐ HASL (PB-FREE) ☐ GOLDEN FINGER
F. IMPEDANCE CONTROL : ☐ NO ☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
G. THROUGH VIA : PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
H. STACK-UP : SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Drill Drawing

.DRL

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,020mm	4,2	
1	Top Layer	Copper	0,018mm		
	Dielectric 2	8 x 7628	1,464mm	4,2	
2	Bottom Layer	Copper	0,018mm		
	Bottom Solder	Solder Resist	0,020mm	4,2	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
	2	0,970mm (38,19mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
	8	1,000mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	20	0,900mm (35,43mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
	398	0,350mm (13,78mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	428 Total						